

CLAIMS

What is claimed is:

5           1. A method of detecting variations in a  
spatially correlated parameter comprising:  
measuring a selected parameter of each of a plurality  
of electronic circuits replicated on a common substrate;  
calculating a difference between a value of the  
10 selected parameter at a target location and that of an  
identical relative location with respect to the target  
location for each of the plurality of electronic circuits  
to generate a distribution of differences;  
calculating an absolute value of the distribution of  
15 differences; and  
calculating an average of the absolute value of the  
distribution of differences to generate a representative  
value for the residual for the identical relative location.

20           2. The method of Claim 1 further comprising  
plotting the residual as a function of the identical  
relative location to determine a spatial correlation  
pattern of the selected parameter.

25           3. The method of Claim 1 wherein the electronic  
circuit is an integrated circuit die and the common  
substrate is a silicon wafer.

30           4. The method of Claim 1 wherein the selected  
parameter is quiescent current.

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5. The method of Claim 1 further comprising performing a lot averaging for each wafer X-Y coordinate so that a new set of best estimates is re-calculated for each X-Y position.

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6. The method of Claim 1 wherein the common substrate comprises a plurality of common substrates wherein best estimates for a given X-Y location are identical to those of a corresponding location on another of the plurality of common substrates. This technique may be improved by re-ordering the wafers in the sequence in which they were processed to ensure more accurate estimation.

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7. The method of Claim 6 further comprising re-ordering the plurality of common substrates in a same order in which they were processed.

8. A process for reducing the variance of a selected parameter in a production lot of integrated circuits comprising:

measuring a selected parameter of each of a plurality of integrated circuit die replicated on a wafer substrate;

calculating a difference between a value of the selected parameter at a target location and that of an identical relative location with respect to the target location for each of the plurality of integrated circuit die to generate a distribution of differences;

calculating an absolute value of the distribution of differences;

calculating an average of the absolute value of the distribution of differences to generate a representative value for the residual for the identical relative location having an expected value range of the selected parameter at  
5 the identical relative location; and

rejecting any of the plurality of integrated circuit die having a value of the selected parameter that lies outside the expected value range.

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10 9. The process of Claim 8 further comprising plotting the residual as a function of the identical relative location to determine a spatial correlation pattern of the selected parameter.

15 10. The process of Claim 8 wherein the selected parameter is quiescent current.